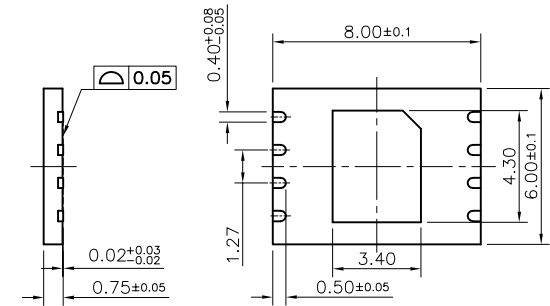
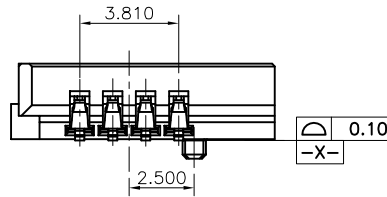
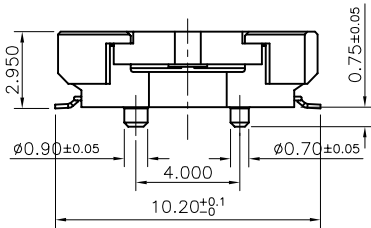
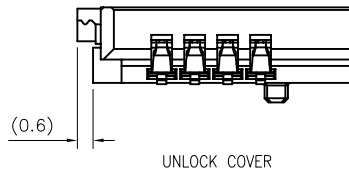
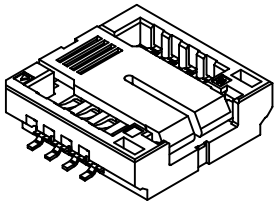


RECOMMEND PCB LAYOUT (TOP VIEW)
GENERAL TOLERANCE ± 0.05



PAD CONFIGURATION LAYOUT

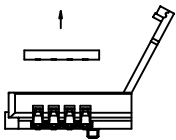
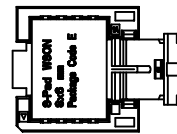
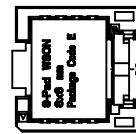
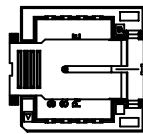
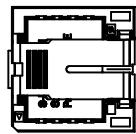
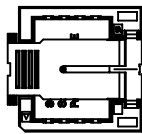
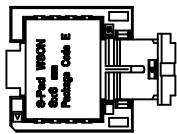
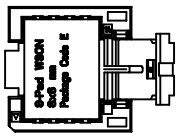
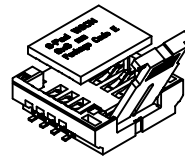
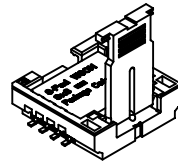
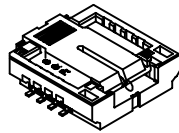
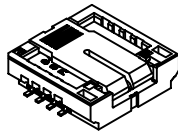
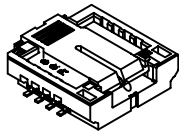
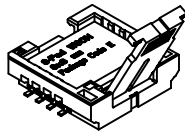
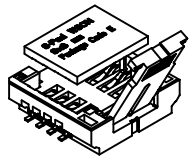


- NOTES:
 1. MATERIAL:
 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:NATURAL.
 1.2 CONTACT: COPPER ALLOY
 1.3 COVER: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
 1.4 MYLAR
 2. FINISH:
 2.1 CONTACT:SEE ORDER INFORMATION.
 UNDERPLATING: 50~100 μ NICKEL OVERALL.
 N: 80~120 μ MATT TIN ON CONTACT AND SOLDER BEAR
 C: 15 μ GOLD ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 4. SPEC. PLS. REFER TO PS-50950-XXXX-XXX
 5. PACKAGE PLS. REFER TO 50950-XXXCR-00
 6. APPLY BASE ON WINBOND W25Q256JV
 7. PART NUMBER

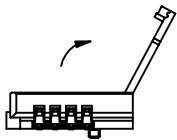
XXX	NOTE
001	WITH BOSS

CKTS: 008:8 PIN
 PACKAGE: N: MATT TIN
 C: 15 μ GOLD ON CONTACT
 4.TAPE&REEL WITH MYLAR

QUALITY SYMBOLS	DRAWN BY	DATE	
MAJOR	Mengmeng	23/03/29	
CRITICAL	CHECKED BY	DATE	TITLE
GENERAL TOLERANCES (UNLESS SPECIFIED)	APPROVED BY	DATE	SOCKET CONN.
X ±0.5	Xu,ZhiYong	23/03/29	UNITS
.X ±0.25			mm
.XX ±0.15			SCALE
.XXX ±0.1			1 : 1
ANGLES ±2°			SHEET NO.
			1 OF 4
			REV
			D
			PART NO.
			50950-XXXX-XXX
			SEE NOTES



STEP 7: TAKE OUT CHIP



STEP 6: OPEN COVER



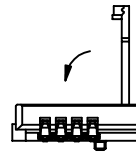
STEP 5: UNLOCK COVER



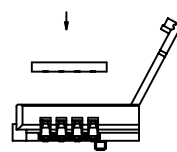
STEP 4



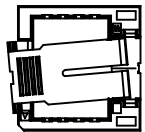
STEP 3: LOCK COVER



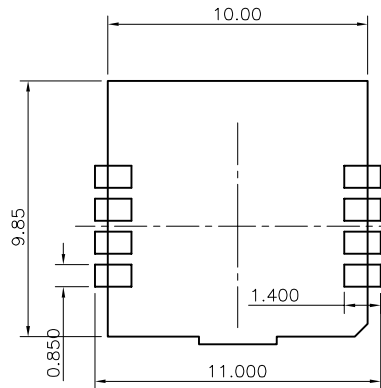
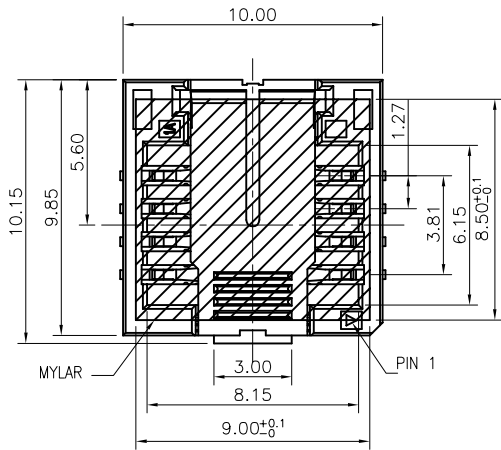
STEP 2: CLOSE COVER



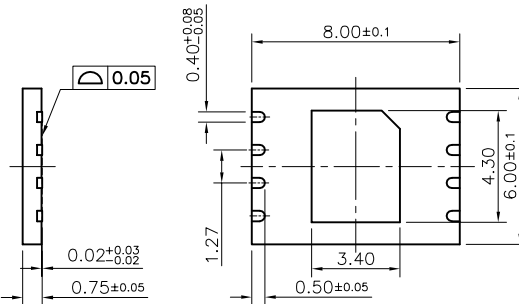
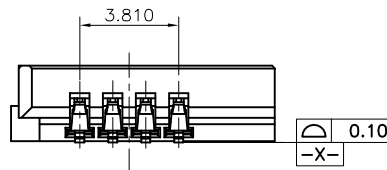
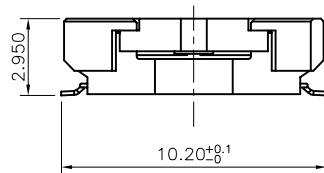
STEP 1: CHIP INSIDE WHEN COVER OPEN



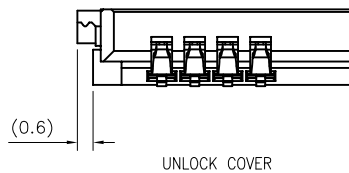
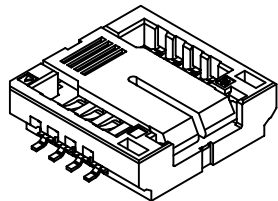
QUALITY SYMBOLS MAJOR \oplus CRITICAL \ominus	DRAWN BY Mengmeng	DATE 23/03/29	
	CHECKED BY Xu,ZhiYong	DATE 23/03/29	
GENERAL TOLERANCES (UNLESS SPECIFIED) .X ± 0.5 .XX ± 0.15 .XXX ± 0.1 ANGLES $\pm 2'$	APPROVED BY Xu,ZhiYong	DATE 23/03/29	DWG NO. 50950-XXXX-XXX
	UNITS mm		SCALE 1:1
	SHEET NO. 2 OF 4	PART NO. SEE NOTES	



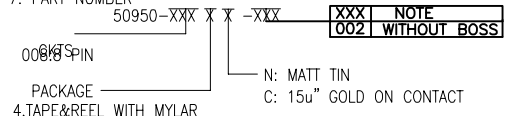
RECOMMEND PCB LAYOUT (TOP VIEW)
GENERAL TOLERANCE ±0.05



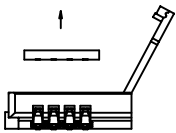
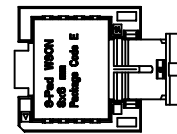
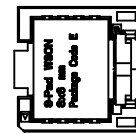
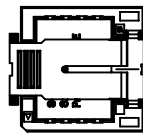
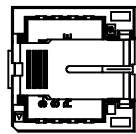
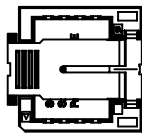
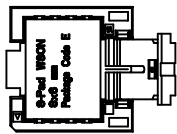
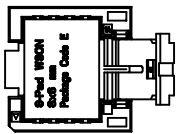
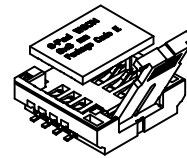
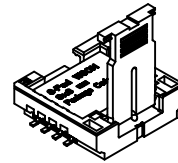
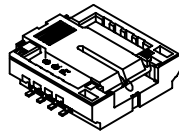
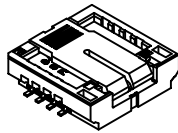
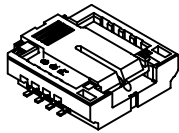
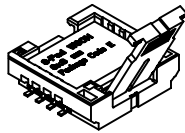
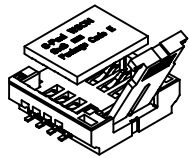
PAD CONFIGURATION LAYOUT



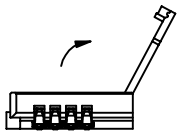
- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:NATURAL.
 - CONTACT: COPPER ALLOY
 - COVER: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
 - MYLAR
 - FINISH:
 - CONTACT:SEE ORDER INFORMATION.
UNDERPLATING: 50~100μ" NICKEL OVERALL.
N: 80~120μ" MATT TIN ON CONTACT AND SOLDER AEAR
C: 15μ" GOLD ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - REFLOW SOLDER CAPABLE TO 260~C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50950-XXXX-XXX
 - PACKAGE PLS. REFER TO 50950-XXXX-00
 - APPLY BASE ON WINBOND W25Q256JV
 - PART NUMBER



QUALITY SYMBOLS	DRAWN BY	DATE	ACES ELECTRONICS
MAJOR Ⓢ	Mengmeng	23/03/29	
CRITICAL Ⓢ	CHECKED BY	DATE	TITLE
GENERAL TOLERANCES (UNLESS SPECIFIED)	APPROVED BY	DATE	SOCKET CONN.
X ±0.05	Xu,ZhiYong	23/03/29	UNITS
.X ±0.025			mm
.XX ±0.015			SCALE
.XXX ±0.01			1 : 1
ANGLES ±2°			SHEET NO.
			3 OF 4
			SIZE
			A4
			REV
			D
			DWG NO.
			50950-XXXX-XXX
			PART NO.
			SEE NOTES



STEP 7: TAKE OUT CHIP



STEP 6: OPEN COVER



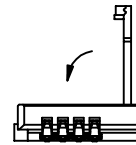
STEP 5: UNLOCK COVER



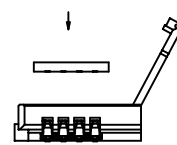
STEP 4



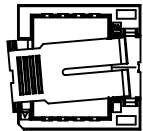
STEP 3: LOCK COVER



STEP 2: CLOSE COVER



STEP 1: CHIP INSIDE WHEN COVER OPEN



QUALITY SYMBOLS MAJOR CRITICAL	DRAWN BY Mengmeng	DATE 23'/03/29	
	CHECKED BY	DATE	
GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY Xu,ZhiYong	DATE 23'/03/29	TITLE SOCKET CONN.
	UNITS mm		SIZE A4
SCALE 1 : 1	SHEET NO. 4 OF 4	REV D	PART NO. SEE NOTES